10/060483 10/060483 01/30/02

ransmitted herewith for filing is the Patent Application of:

Inventor: YEN-MING CHEN, CHIA-FU LIN, SHUN LIANG HSU, KAI-MING CHING, HSIN-HUI LEE,

CHAO-YUAN SU, LI-CHIH CHEN

ir:

For: NOVEL METHOD TO IMPROVE BUMP RELIABILITY FOR FLIP CHIP DEVICE

Enclos	ed are:							
x	<u>5</u> sheets	s of drawing(s)	- formal.					
<del>grant</del>	An assign	nment of the i	nvention to 1	Taiwan Semiconduc	ctor Manufactu	ring Company		
	An associate power of attorney Applicant claims small entity status							
×	Request &	Certification	n under 35 US	SC 122(b)(2)(b)(	i)			
The fi	ling fee	has been calc	ulated as sho	own below:				
		(Col. 1)	(Col. 2)		SMALL ENTITY	1		
FOR:		NO. FILED	NO. EXTRA	RATE	FEE			
BASIC	FEE				\$ 740.			
TOTAL	CLAIMS	<b>28</b> -20=	8	x 18 =	\$ 144.			
INDE	CLAIMS	<b>2</b> -3=	0	x 84 =	\$ 0.			
	MULTIPLE	DEPENDENT CLA	IM PRESENTED	+ 260 =				
				SUB TOTAL	\$ 884.			
				ASSIGNMENT	\$40.			
				TOTAL	\$ 924.			
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	The Commissioner is hereby authorized to charge payment of the following fees							
	associated with this communication or credit any overpayment to Deposit Account No.							
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19-0033. A duplicate copy of this sheet is enclosed.  X Any additional filing fees required under 37 CFR \$1.16.  X Any patent application processing fees under 37 CFR \$1.17.								
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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231. Applicant and/or

Attorney requests the date of deposit as the Filing Date.

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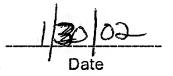
NONPUBLICATION REQUEST UNDER 35 U.S.C. 122(b)(2)(B)(i)

First N	Named Inventor	Yen-Ming Chen
Title	Novel Me Reliability	thed To Improve Bump for Flip Chip Device
Atty D	Oocket Number	TEN 1/12

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

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Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).

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